



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)}	I _D T _A = +25°C
001/	2Ω @ V _{GS} = 4V	320mA
60V	2.5Ω @ V _{GS} = 2.5V	50mA

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- DC-DC Converters
- Power Management Functions
- Battery Operated Systems and Solid-State Relays
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.

Mechanical Data

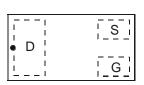
- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.001 grams (Approximate)



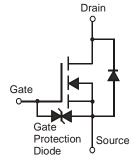




Bottom View



Top View Pin-Out



Equivalent Circuit

Ordering Information (Note 4)

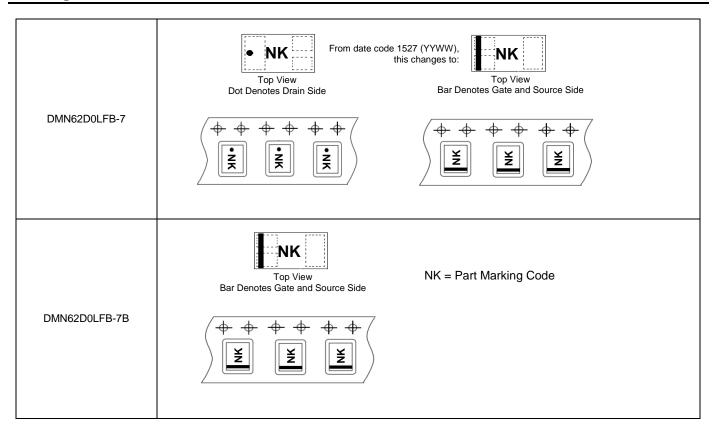
Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DMN62D0LFB-7	NK	7	8	3,000
DMN62D0LFB-7B	NK	7	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Character	Symbol	Value	Unit		
Drain-Source Voltage	V_{DSS}	60	V		
Gate-Source Voltage	V _{GSS}	±20	V		
Continuous Drain Current (Note 5) V _{GS} = 4.0V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	320 75	mA
Pulsed Drain Current (Note 6)	I _{DM}	1	Α		

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 5)	P _D	0.5	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	$R_{\theta JA}$	258	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes: 5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.

6. Repetitive rating, pulse width limited by junction temperature.

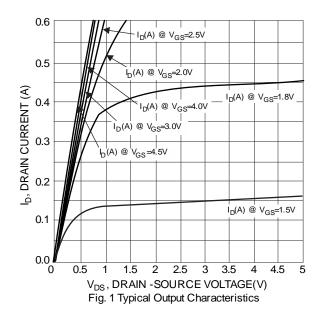


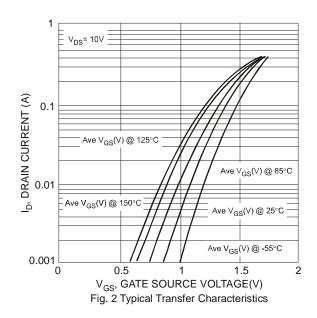
Electrical Characteristics (@ T_A = +25°C, unless otherwise stated.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	60	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	-	-	1.0	μΑ	$V_{DS} = 60V, V_{GS} = 0V$	
	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 5V$, $V_{DS} = 0V$	
Gate-Source Leakage		-	-	±500	nA	$V_{GS} = \pm 10V$, $V_{DS} = 0V$	
		-	-	±2.0	μΑ	$V_{GS} = \pm 15V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	0.6	-	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
		-	1.3	2		$V_{GS} = 4V, I_{D} = 100mA$	
Static Drain-Source On-Resistance	D	-	1.5	2.5	Ω	$V_{GS} = 2.5V, I_D = 50mA$	
Static Dialii-Source Off-Resistance	R _{DS(ON)}	-	1.9	3	Ω	$V_{GS} = 1.8V, I_D = 50mA$	
		-	2.6	-		$V_{GS} = 1.5V, I_D = 10mA$	
Forward Transfer Admittance	Y _{fs}	-	0.8	-	S	$V_{DS} = 10V, I_D = 200mA$	
Diode Forward Voltage	V _{SD}	-	0.9	1.3	V	$V_{GS} = 0V, I_{S} = 115mA$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	-	32	64)/ OF)/)/ O)/	
Output Capacitance	Coss	-	4.4	9	рF	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	-	2.9	6		I = I.OWIHZ	
Gate Resistance	Rg	-	126	250	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg	-	0.45	0.9			
Gate-Source Charge	Qgs	-	0.08	0.2	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$	
Gate-Drain Charge	Q_{gd}	-	0.08	0.2		$I_D = 250 \text{mA}$	
Turn-On Delay Time	t _{D(ON)}	-	3.4	10	ns		
Turn-On Rise Time	t _R	-	3.4	10	ns	$V_{GS} = 10V, V_{DS} = 30V,$	
Turn-Off Delay Time	t _{D(OFF)}	-	26.4	45	ns	$R_L = 150\Omega, R_g = 25\Omega,$	
Turn-Off Fall Time	t _F	-	16.3	30	ns	$I_D = 200 \text{mA}$	

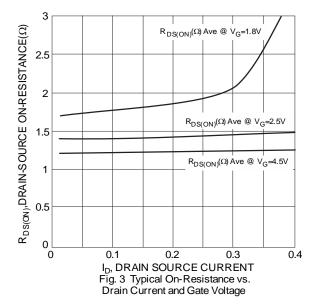
Notes:

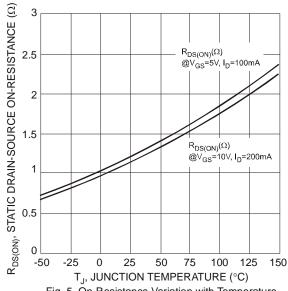
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.

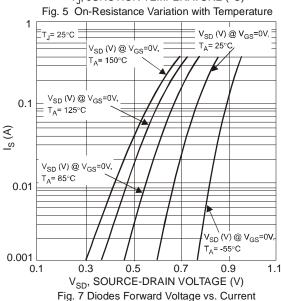


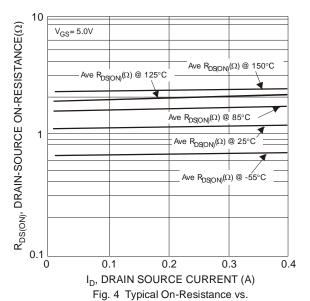






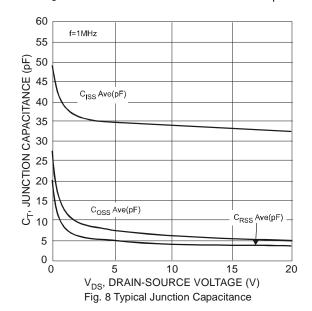




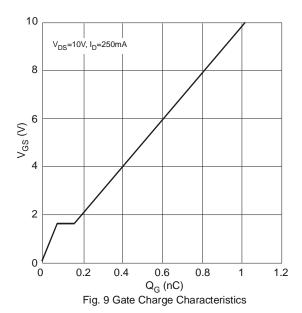


Drain Current and Temperature 1.6 $V_{TH}(V) @ I_D=1mA$ V_{TH}, GATE THRESHOLD VOLTAGE (V) 1.2 8.0 0.6 0.2 -50 -25 0 25 50 75 100 125 T_J, JUNCTION TEMPERATURE (°C)

Fig. 6 Gate Threshold Variation vs. Junction Temperature







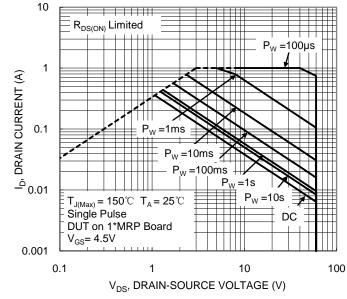


Fig.10 SOA, Safe Operation Area

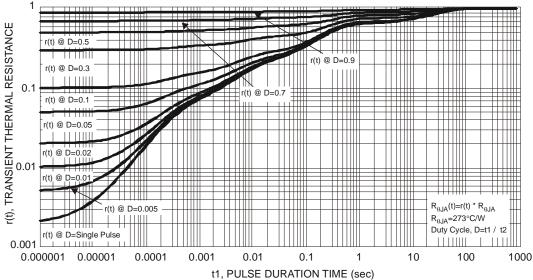
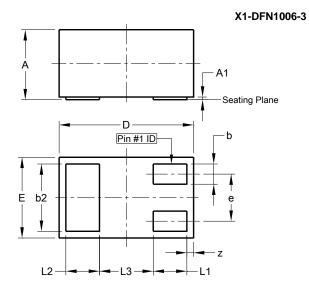


Fig. 11 Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

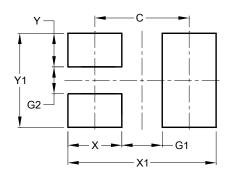


X1-DFN1006-3				
Dim	Min	Max	Тур	
Α	0.47	0.53	0.50	
A1	0.00	0.05	0.03	
b	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
ם	0.95	1.075	1.00	
E	0.55	0.675	0.60	
e	ı	-	0.35	
L1	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3	-	-	0.40	
Z	0.02	0.08	0.05	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1006-3



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Υ	0.25
Y1	0.70



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